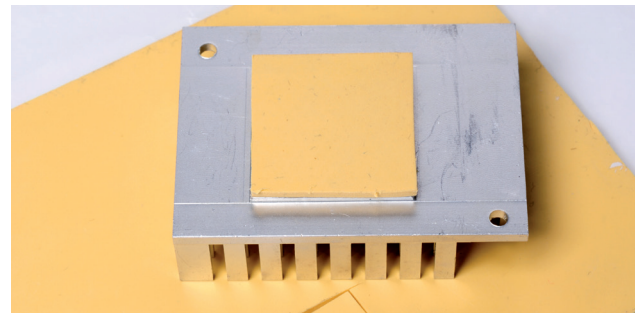


THERMAL PAD - DT25

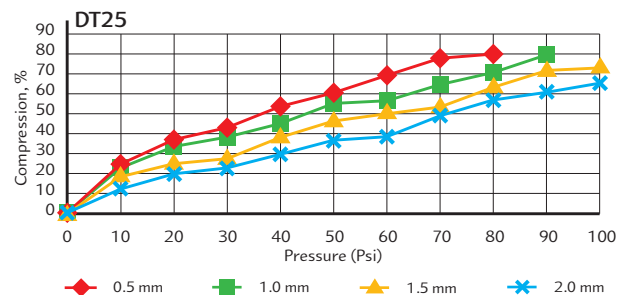
Features

- Thermal conductivity: 2.5 W/mK
- High conformability
- Cost effective solution
- Electrically insulating
- Naturally sticky
- High dielectric breakdown of up to 5.0 kV/mm
- Custom die-cut parts: custom configurations available



Applications

- Between electronic components: semiconductors, ICs, CPUs, MOS and heatsink
- LEDs, LCD TV, telecom devices, wireless hubs, PCs, power supplies etc.
- Cooling and thermal modules
- In all applications where a metal housing is used as heatsink.



Part number code (example):

UDT 10/H10 - T 10

- Thickness: 1.0 mm
- Hardness: 10 Shore C
- Thermal Conductivity: 1.0 W/mK
- UDT: Thermal Pad

TECNITE DT25

Properties	Unit	DT25	Test Method
Composition		Silicone & ceramic filled	
Colour		Light yellow	
Thickness range	mm	0.5 - 5.0	
Hardness	Shore C	25	ASTM D2240
Density	g/ml	2.93	ASTM D792
Elongation	%	72	ASTM D412
Temperature range	°C	-40 to 150	EN344
Breakdown voltage	kV/mm	≥5.0	ASTM D149
Volume impedance	ohm*cm	3.2*10 ¹⁶	ASTM D257
Dielectric constant	@ 1 MHz	6.3	ASTM D150
Weight dampify	%	≥0.5	@ 150 °C 240H
Thermal conductivity	W/mK	2.5	ASTM E1461
Thermal Resistance @ 40 psi	°C-in ² /W	0.355 @ 0.5 mm 0.542 @ 1.0 mm	
Compliances		UL 94 V-0, RoHS, REACH	
Sheet sizes		Standard: 200*400 mm, 330*330 mm	
Custom configurations		Custom die-cut parts available. Available with acrylic PSA tape for improved application on one or both sides: • 3M Double Coated Tape 9448HK (will make the pad 0.15 mm thicker on both sides) • 3M Transfer Tape 3M467 (will make the pad 0.06 mm thicker on both sides)	

DISTRIBUTORS GROUP EUROPE

Handelsweg 6, NL - 2404 CD Alphen aan den Rijn, The Netherlands
Tel. 0031-172-436361 Fax 0031-172-420310
info@dge-europe.com www.dge-europe.com

